502855856 06/17/2014

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2902453

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Hong-Ta Hsu	06/17/2014

#### **RECEIVING PARTY DATA**

Name:	Realtek Semiconductor Corp.	
Street Address:	2 Innovation Rd. II, Science Park	
City:	HsinChu	
State/Country:	TAIWAN	

# **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	14307475	

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NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	06/17/2014

**Total Attachments: 2** source=1981048#page1.tif source=1981048#page2.tif

PATENT 502855856 REEL: 033123 FRAME: 0184

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

### Title of Invention:

METHOD AND APPARATUS FOR ESTIMATING SAMPLING DELAY ERROR BETWEEN FIRST AND SECOND ANALOG-TO-DIGITAL CONVERTERS OF TIME-INTERLEAVED ANALOG-TO-DIGITAL CONVERTER

As the below named inventor, I hereby declare that: This declaration is directed to:					
☑ The attached application, or					
☐ United States application number	filed on	, or			
☐ PCT international application number	filed on				
The above-identified application was made or authorized to	be made by me.				
I believe that I am the original inventor or an original joint invapplication.	ventor of a claimed invention in	n the			
I hereby acknowledge that any willful false statement made in under18 U.S.C. 1001 by fine or imprisonment of not more the	in this declaration is punishab an five (5) years, or both.	le			
In consideration of the payment by Realtek Semicondo	uctor Corp. having a po	ostal address of			
2 Innovation Rd. II, Science Park, HsinChu 30076	i, Taiwan, R.O.C.				
(referred to as "ASSIGNEE"below) to I of the sum of One Do acknowledged, andfor other good and valuable consideration	ollar (\$ 1.00), the receipt of wh	ich is hereby			
I hereby sell, assign and transfer to ASSIGNEE and the suct the entire right, title and interest in and to any and all improvinvention as above-identified application and, in and to, all Landson by the above application or any continuations, contable substitutes, or extensions thereof, and as to Letters Patent a	ements which are disclosed in etters Patent to be obtained fo tinuation-in-part, divisions, rer	n the or said newals.			
I hereby covenant that no assignment, sale, agreement or entered into which would conflict with this assignment;	ncumbrance has been or will I	be made or			
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instruments or affidavits maintain, issue and enforce said application, said invention a equivalents thereof which may be necessary or desirable to IN WINTNESS WHEREOF, I have hereunto set hand and se	and said Letters Patent and sa carry out the proposes thereo	aid f. (Date of signing) —			
Note: An application data sheet (PTO/SB/14 or equivalent), inventive entity, must accompany this form. Use this form for	including naming the entire reach additional inventor.				

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NPO#REA-P0759-USA:0 CUST#101A-036US F#NPO-P0002E-US1201 DSC0-102U010986

## Docket No REAP0759USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Hong-Ta Hsu

Date:

JUN 1 7 2014

Signature: Hong-Tatisu

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**PATENT REEL: 033123 FRAME: 0186** 

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RECORDED: 06/17/2014